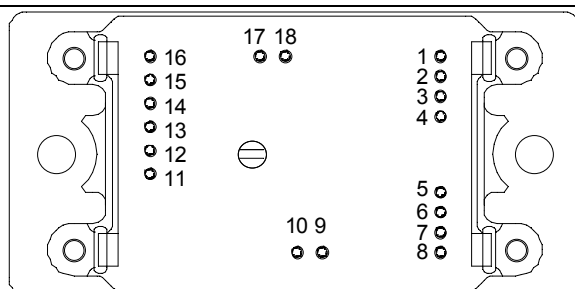
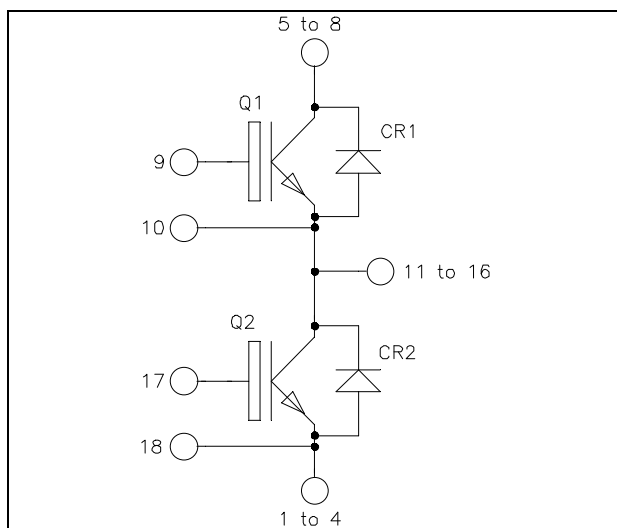


Phase leg
Fast Trench + Field Stop IGBT3
Power Module

$V_{CES} = 1200V$
 $I_C = 75A @ T_c = 80^\circ C$



Pins 1/2/3/4 ; 5/6/7/8 ; 11/12/13/14/15/16
 must be shorted together

Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features

- Fast Trench + Field Stop IGBT3 Technology
 - Low voltage drop
 - Low tail current
 - Switching frequency up to 20 kHz
 - Soft recovery parallel diodes
 - Low diode VF
 - Low leakage current
 - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- Very low stray inductance
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive T_C of V_{CEsat}
- RoHS Compliant

All ratings @ $T_j = 25^\circ C$ unless otherwise specified

Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{CES}	Collector - Emitter Breakdown Voltage	1200	V
I_C	Continuous Collector Current	$T_C = 25^\circ C$	110
		$T_C = 80^\circ C$	75
I_{CM}	Pulsed Collector Current	$T_C = 25^\circ C$	175
V_{GE}	Gate - Emitter Voltage	± 20	V
P_D	Maximum Power Dissipation	$T_C = 25^\circ C$	357
RBSOA	Reverse Bias Safe Operating Area	$T_j = 125^\circ C$	150A @ 1150V

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I_{CES}	Zero Gate Voltage Collector Current	$V_{GE} = 0V, V_{CE} = 1200V$			50	μA
$V_{CE(sat)}$	Collector Emitter saturation Voltage	$V_{GE} = 15V$ $I_C = 75A$	$T_j = 25^\circ C$ $T_j = 125^\circ C$	1.4 2.0	2.1	V
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}, I_C = 3mA$	5.0		6.5	V
I_{GES}	Gate – Emitter Leakage Current	$V_{GE} = 20V, V_{CE} = 0V$			400	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{ies}	Input Capacitance	$V_{GE} = 0V$		5340		pF
C_{oes}	Output Capacitance	$V_{CE} = 25V$		280		
C_{res}	Reverse Transfer Capacitance	$f = 1MHz$		240		
Q_G	Gate charge	$V_{GE} = \pm 15V, I_C = 75A$ $V_{CE} = 600V$		0.70		μC
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching ($25^\circ C$) $V_{GE} = \pm 15V$ $V_{Bus} = 600V$ $I_C = 75A$ $R_G = 4.7\Omega$		260		ns
T_r	Rise Time			30		
$T_{d(off)}$	Turn-off Delay Time			420		
T_f	Fall Time			70		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching ($125^\circ C$) $V_{GE} = \pm 15V$ $V_{Bus} = 600V$ $I_C = 75A$ $R_G = 4.7\Omega$		285		ns
T_r	Rise Time			50		
$T_{d(off)}$	Turn-off Delay Time			520		
T_f	Fall Time			90		
E_{on}	Turn-on Switching Energy	$V_{GE} = \pm 15V$ $V_{Bus} = 600V$ $I_C = 75A$ $R_G = 4.7\Omega$	$T_j = 125^\circ C$	7		mJ
E_{off}	Turn-off Switching Energy		$T_j = 125^\circ C$	8.1		
I_{sc}	Short Circuit data	$V_{GE} \leq 15V; V_{Bus} = 900V$ $t_p \leq 10\mu s; T_j = 125^\circ C$		300		A
R_{thJC}	Junction to Case Thermal Resistance				0.35	$^\circ C/W$

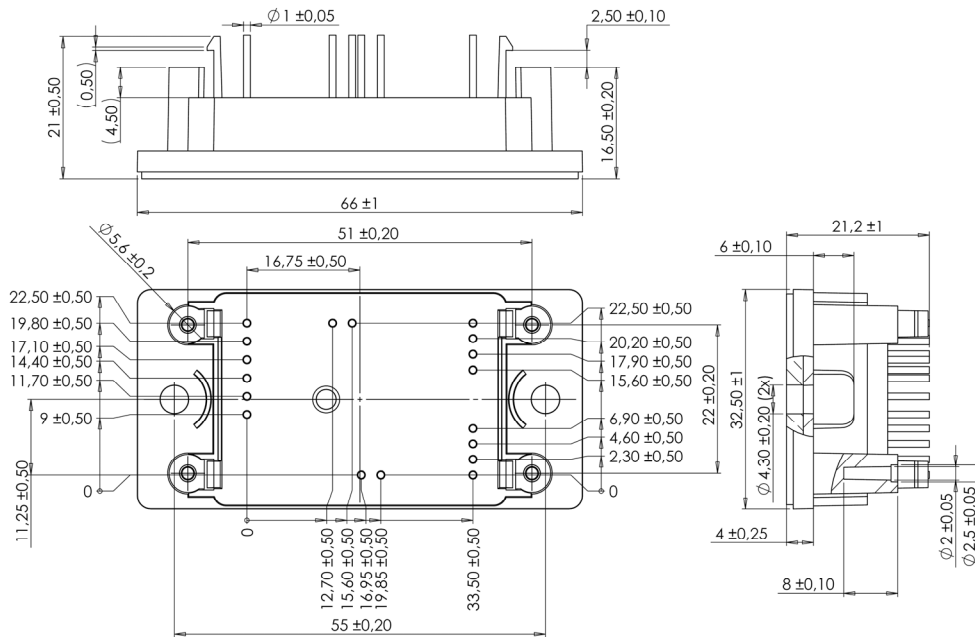
Reverse diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V_{RRM}	Maximum Peak Repetitive Reverse Voltage		1200			V
I_{RM}	Maximum Reverse Leakage Current	$V_R = 1200V$			50	μA
I_F	DC Forward Current	$T_c = 80^\circ C$		75		A
V_F	Diode Forward Voltage	$I_F = 75A$	$T_j = 25^\circ C$ $T_j = 125^\circ C$	1.6 1.6	2.1	V
t_{rr}	Reverse Recovery Time	$I_F = 75A$ $V_R = 600V$ $di/dt = 2000A/\mu s$	$T_j = 25^\circ C$ $T_j = 125^\circ C$	170 280		ns
Q_{rr}	Reverse Recovery Charge		$T_j = 25^\circ C$ $T_j = 125^\circ C$	7 14		μC
E_r	Reverse Recovery Energy		$T_j = 25^\circ C$ $T_j = 125^\circ C$	2.8 5.4		mJ
R_{thJC}	Junction to Case Thermal Resistance				0.58	$^\circ C/W$

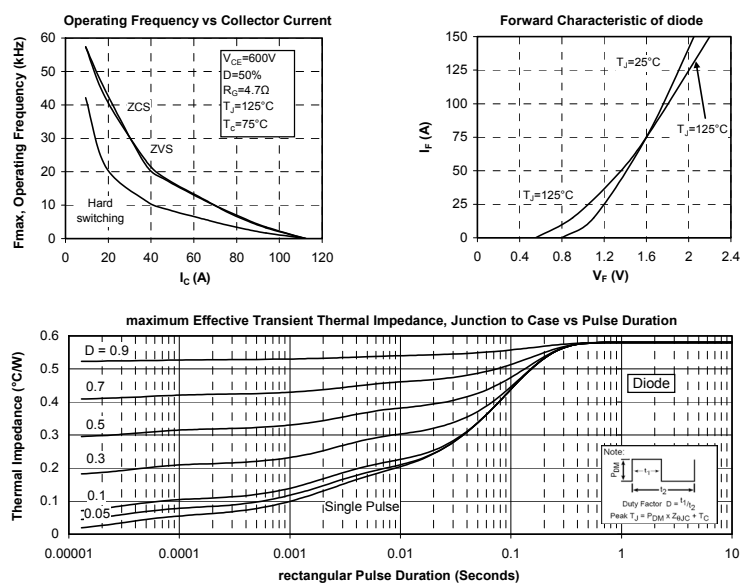
Thermal and package characteristics

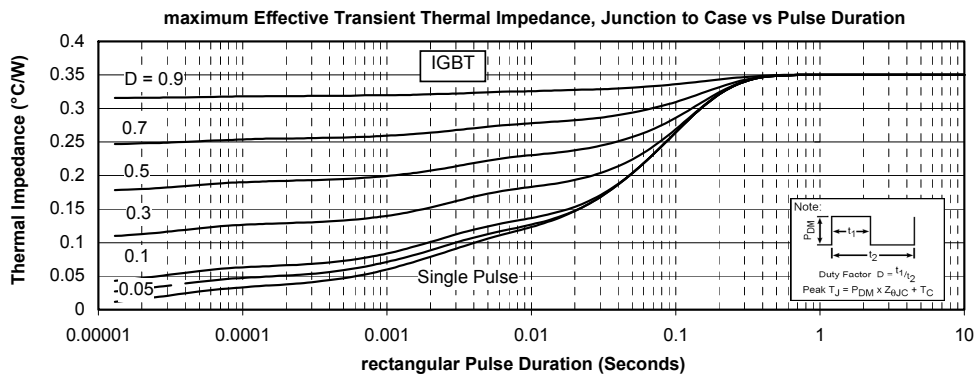
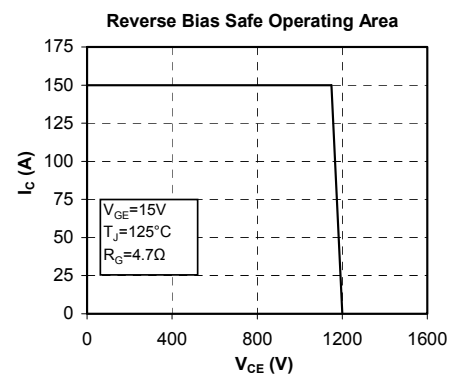
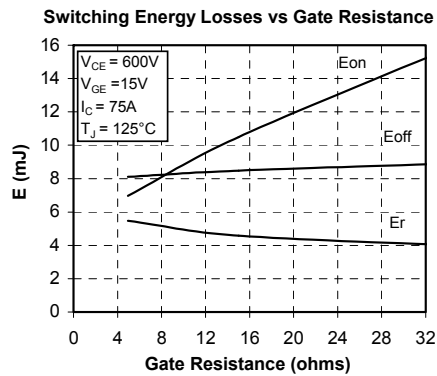
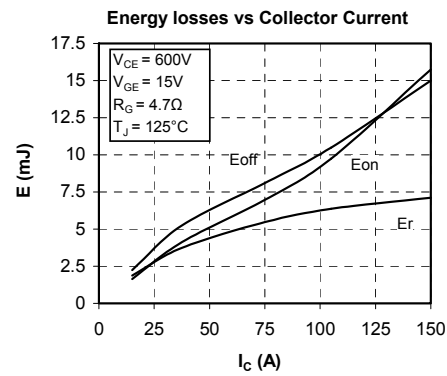
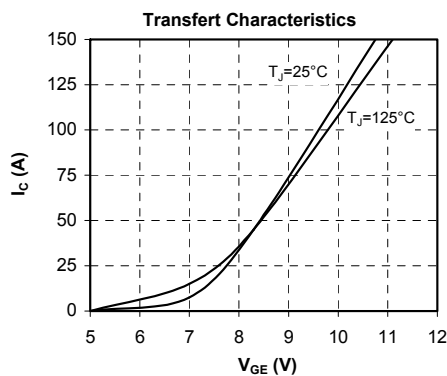
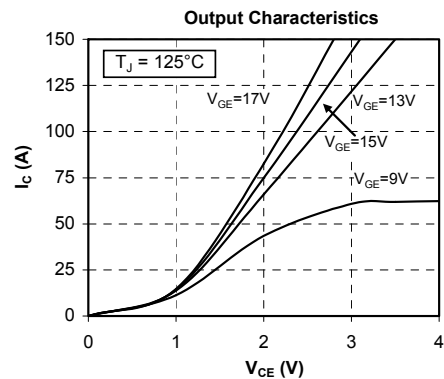
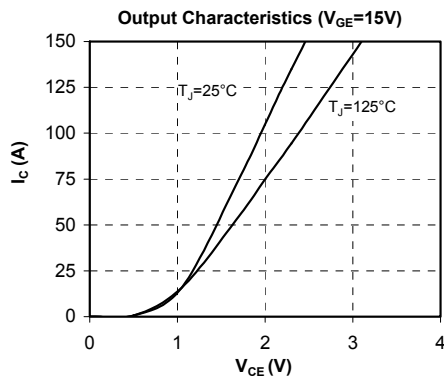
Symbol	Characteristic			Min	Typ	Max	Unit
V _{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T _J	Operating junction temperature range			-40		150	°C
T _{STG}	Storage Temperature Range			-40		125	
T _C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M4	2		3	N.m
Wt	Package Weight					75	g

SP2 Package outline (dimensions in mm)



Typical Performance Curve





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